

ABSTRACT

An assembly method that includes providing a first semiconductor device with discrete conductive elements protruding above a surface thereof and positioning a second semiconductor device at least partially over the first semiconductor device. A back side of the second semiconductor device rests upon at least some of the discrete conductive elements while remaining electrically isolated therefrom. The first and second semiconductor devices may be secured to one another with an adhesive material which is either placed on an active surface of the first semiconductor device before positioning the second semiconductor device thereover or introduced between the first and second semiconductor devices. Assemblies and packaged semiconductor devices that are formed in accordance with the method are also disclosed.

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